

**IPC J-STD-001F**

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# ***JOINT INDUSTRY STANDARD***

Requirements for  
Soldered Electrical  
and Electronic  
Assemblies



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# Requirements for Soldered Electrical and Electronic Assemblies

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A joint standard developed by the J-STD-001 development team including Task Group Europe (5-22A), Task Group Asia (5-22ACN) and Task Group India (5-22AIN) of the Assembly and Joining Committees (5-20 and 5-20CN) of IPC.

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**Contact:**

**IPC**

3000 Lakeside Drive, Suite 309S  
Bannockburn, IL 60015-1249  
Phone ( 847) 615-7100  
Fax (847) 615-7105

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### Assembly and Joining Committee

Chair

Leo P. Lambert

Eptac Corporation

Vice Chair

Renee J. Michalkiewicz

Trace Laboratories - Baltimore

### J-STD-001

#### Task Group

Co-Chairs

Teresa M. Rowe

Daniel L. Foster

Missile Defense Agency

### Technical Liaison of the IPC Board of Directors

Bob Neves

Microtek (Changzhou) Laboratories

### J-STD-001

#### Task Group – China

Chair

Zhang Yuan

Huawei Technologies Co., Ltd.

### J-STD-001

#### Task Group – India

Chair

I. S. Nanjundaswamy

IPC Technology

Consulting Pvt Ltd

### Members of J-STD-001 Task Group (5-22A)

Jon Roberts

Doug Rogers

Teresa Rowe

Donald McFarland, 3i

Arye Grushka, A. A. Training Consulting and Trade A.G. Ltd.

Alejandro Cruz, ACME Training & Consulting

Tim Brown, ACME Training & Consulting

Constantino Gonzalez, ACME Training & Consulting

Rhonda Troutman, Actron, Inc

Debbie Wade, Advanced Rework Technology-A.R.T.

John Vickers, Advanced Rework Technology-A.R.T.

Michael Wierleski, Aerojet Rocketdyne

Sam Goeller, Aerojet Rocketdyne

Joseph Smetana, Alcatel-Lucent

Kensell Nowland, Alcatel-Lucent

Ronald McIlroy, American General Contracting

Sean Keating, Amphenol Limited (UK)

Bruce Hughes, Amrdec E&S&T EPPT

Christopher Sattler, AQS - All Quality & Services, Inc.

Bill Strachan, ASTA - Portsmouth University

Mark Shuman, ATK Armament Systems

Agneszka Ozarowski, BAE Systems

Joseph Kane, BAE Systems Platform Solutions

Marvin Banks, Ball Aerospace & Technologies Corp.

Jonathon Vermillion, Ball Aerospace & Technologies Corp.

Andre Baune, Bautech Inc.

Gerald Leslie Bogert, Bechtel Plant Machinery Inc.

Vinay Goyal, Beckman Coulter Inc.

Norman Mier, BEST Inc.

Robert Wettermann, BEST Inc.

Dorothy Cornell, Blackfox Training Institute

Jay Messner, Boeing Company

Karl Mueller, Boeing Company

Thomas Carroll, Boeing Company

Edward Cuneo, Boeing Company

Joseph Riendeau, Boeing Research & Development

Mary Bellon, Boeing Research & Development

Jack Olson, Caterpillar Inc.

Zenaida Valianu, Celestica

Alanis Heriberto, Chamberlain

Angel Deluna, Circuit Technology Inc.

Steven Perng, Cisco Systems Inc.

Marilyn Lawrence, Conformance Technologies, Inc.

Israel Martinez, Continental Automotive Nogales S.A. de C.V.

Laura Cote, Continental Automotive Systems

Cynthia Gomez, Continental Temic SA de CV

Jose Servin, Continental Temic SA de CV

Miguel Dominguez, Continental Temic SA de CV

Mary Muller, Crane Aerospace & Electronics

John Marshall, dataCon Inc.  
 Lowell Sherman, Defense Supply Center Columbus  
 Wallace Ables, Dell Inc.  
 John Borneman, Delphi Electronics and Safety  
 Irene Romero, Delta Group Electronics Inc.  
 Michael Mora, Delta Group Electronics Inc.  
 Vicki Hagen, Delta Group Electronics Inc.  
 Gabriel, Rosin, Elbit Systems Ltd.  
 Pam McCord, Elbit Systems of America  
 Yaakov Zissman, Elta Systems Ltd.  
 Imelda Avila, EPIC Technologies  
 Helena Pasquito, EPTAC Corporation  
 Leo Lambert, EPTAC Corporation  
 Barrie Dunn, European Space Agency  
 Nancy Chism, Flextronics  
 Omar Karin Hernandez, Flextronics Manufacturing Mex, SA de CV  
 Eric Camden, Foresite, Inc.  
 Terry Munson, Foresite, Inc.  
 Stephen Fribbins, Fribbins Training Services  
 Gary Ferrari, FTG Circuits  
 Graham Naisbitt, Gen3 Systems Limited  
 Richard Stadem, General Dynamics Advanced Information Systems  
 Deepak Pai, General Dynamics Info. Sys. Inc  
 Kristen Troxel, Hewlett-Packard Company  
 Elizabeth Benedetto, Hewlett-Packard Company  
 Curtis Wray, Hewlett-Packard Company  
 John Pickett, Honeywell Aerospace  
 John Mastorides, Honeywell Aerospace  
 Amir Began, Honeywell Canada  
 Richard Thomas, Honeywell Canada  
 William Novak, Honeywell International  
 Riley Northam, Honeywell Technology Solutions Inc.  
 Jennie Hwang, H-Technologies Group  
 Zhang Yuan, Huawei Technologies Co., Ltd.  
 Poul Juul, HYTEK  
 Bert El-Bakri, Inovar, Inc.  
 Jagadeesh Radhakrishnan, Intel Corporation  
 John Yu, I-SAC Electronic Co. Ltd.  
 Ricardo Moncaglieri, INVAP SE  
 Alan Young, Jet Propulsion Laboratory  
 Reza Ghaffarian, Jet Propulsion Laboratory  
 Frank Hules, Johanson Dielectrics Inc.  
 Akikazu Shibata, JPCA-Japan Electronics Packaging and Circuits Association  
 Nancy Bullock-Ludwig, Kimball Electronics  
 Augustin Stan, L&G Advice Serv SRL  
 Leopold Whiteman, L-3 Communications  
 Shelley Holt, L-3 Communications  
 Robert Fornefeld, L-3 Communications  
 Keld Maaloe, LECO Systems A/S  
 Josh Goolsby, Lockheed Martin  
 Linda Wood, Lockheed Martin Missile & Fire Control  
 Vijay Kumar, Lockheed Martin Missile & Fire Control  
 Roger Buisson, Lockheed Martin Missiles & Fire Control  
 Sam Polk, Lockheed Martin Missiles & Fire Control  
 Sharissa Johns, Lockheed Martin Missiles & Fire Control  
 Kimberly Shields, Lockheed Martin Mission Systems & Training  
 Pamela Petcosky, Lockheed Martin Mission Systems & Training  
 Steven Nolan, Lockheed Martin Mission Systems & Training  
 Dominik Alder, Lockheed Martin Space Systems Company  
 Neil Wolford, Logic PD  
 Daniel Foster, Missile Defense Agency  
 Bill Kasprzak, Moog Inc.  
 William Draper, Moog Inc.  
 Edward Rios, Motorola Solutions  
 Jeannette Plante, NASA Goddard Space Flight Center  
 Robert Humphrey, NASA Goddard Space Flight Center  
 Anthony Wong, NASA Johnson Space Center  
 Robert Cooke, NASA Johnson Space Center  
 Scott Worley, NASA Marshall Space Flight Center  
 James Blanche, NASA Marshall Space Flight Center  
 Charles Gamble, NASA Marshall Space Flight Center  
 Adam Gowan, NASA Marshall Space Flight Center  
 Garyvic Gure, NASA Marshall Space Flight Center  
 Mahendra Gandhi, Northrop Grumman Aerospace Systems  
 Randy McNutt, Northrop Grumman Corp.  
 Mac Butler, Northrop Grumman Corporation  
 Tana Soffa, Northrop Grumman Corporation  
 Doris McGee, Northrop Grumman Corporation  
 Toshiyasu Takei, NSK Co., Ltd.  
 Kenneth Lee, NSWC - Corona  
 Andrew Ganster, NSWC Crane  
 Gary Latta, NSWC Crane  
 Eric Scott, NSWC Crane  
 Joseph Sherfick, NSWC Crane  
 William May, NSWC Crane  
 Angela Pennington, NuWaves Engineering  
 Brian Langley, OK International  
 Ken Moore, Omni Training Corp.  
 Raymond Falkenthal, Optimum Design Associates  
 Gustavo Arredondo, Para Tech Coating Inc.  
 Matt Garrett, Phonon Corporation  
 Ron Fonsaer, PIEK International Education Centre (I.E.C.) BV

Frank Huijsmans, PIEK International Education Centre (I.E.C.) BV	Steven Herrberg, Raytheon Systems Company	Patricia Scott, STI Electronics, Inc.
Rob Walls, PIEK International Education Centre (I.E.C.) BV	Linda Haining Hall, Raytheon UK	Floyd Bertagnolli, STM - Service To Mankind
Kirk Van Dreel, Plexus Corp.	Paula Jackson, Raytheon UK	Terry Clitheroe, Surface Mount Circuit Board Association
Richard Kraszewski, Plexus Corp.	Udo Welzel, Robert Bosch GmbH	Andres Ojalill, Tallinn Polytechnic School
Sam Theabo, Plexus Corporation	Lisa Cottone, Robins AFB	Tracy Clancy Vecchiolli, Technical Training Center
Timothy Pitsch, Plexus Corporation	Caroline Ehlinger, Rockwell Collins	Steven Kummerl, Texas Instruments Inc.
Bill Barthel, Plexus Manufacturing Solutions	Douglas Pauls, Rockwell Collins	Katie Feistel, The Aerospace Corporation
Guy Ramsey, R & D Assembly	David Hillman, Rockwell Collins	Calette Chamness, U.S. Army Aviation & Missile Command
Lisa Maciolek, Raytheon Company	David Adams, Rockwell Collins	David Carlton, U.S. Army Aviation & Missile Command
Steven Corkery, Raytheon Company	Gary Roper, Roper Resources, Inc.	Jennifer De, CGI Federal
James Saunders, Raytheon Company	Greg Hurst, RSI, Inc.	Sharon Pentless, U.S. Army Aviation & Missile Command
David Nelson, Raytheon Company	Neil Johnson, Saab - Electronic Defence Systems	Heidi Havelka, Unipower Corporation
Michael Blige, Raytheon Company	Casimir Budzinski, Safari Circuits Inc.	Scott Meyer, UTC Aerospace Systems
Lynn Krueger, Raytheon Company	Alisha Asbell, SAIC	Constantin Hudon, Varitron Technologies Inc.
Charles Gibbons, Raytheon Company	Gaston Hidalgo, Samsung Telecommunications America	Gabriela, Ventana Medical Systems
David Tucker, Raytheon Company	Mary James, Schlumberger Well Services	Linda Tucker-Evoniuk, Vergent Products, Inc.
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Fonda Wu, Raytheon Company	Finn Skaanning, Skaanning Quality & Certification -SQC	Lionel Fullwood, WKK Distribution Ltd.
James Daggett, Raytheon Company	Craig Pfefferman, Southern California Braiding Company Inc.	
Kathy Johnston, Raytheon Missile Systems	Gregg Coates, Space Exploration Technologies	
Lance Brack, Raytheon Missile Systems	Paul Hodgeon, STEM Training	
George Millman, Raytheon Missile Systems	Mer Parrish, STI Electronics, Inc.	
Robert Morris, Raytheon Missile Systems		
William Russell, Raytheon Professional Services LLC		
Patrick Kane, Raytheon System Technology		

---

**Members of J-STD-001 Task Group – China (5-22ACN)**

He Yun	Tu Yunhua (Danny), Huawei Technologies Co., Ltd.	Sun Learner, Jabil Circuit (Shanghai) Ltd.
Zhou Guanjun	Gong Peter, Huawei Technologies Co., Ltd.	Wan Yi, Jabil Circuit (Shanghai) Ltd.
Cao Yanling, Alcatel-Lucent Shanghai Bell Co., Ltd.	Cao Xi, Huawei Technologies Co., Ltd.	Li Liyi, Jabil Circuit (Shanghai) Ltd.
Liu Zhifeng, Beijing Dinghan Technology Co., Ltd	He Dapeng, Huawei Technologies Co., Ltd.	Zhao Johnson (Songtao), ShenZhen Easyway Science & Technology Co. Ltd.
Zhou Jia, Emerson Network Power Co. Ltd.	Zhou Huilin, Huawei Technologies Co., Ltd.	Luo Jinsong, Shenzhen KaiFa Technology Co., Ltd.
Zhao, Charlie, Emerson Network Power Co. Ltd.	Chen Yenchu, Integrated Service Technology (Kunshan)	Jia Bianfen, ZTE Corporation
Zhang Cylin, Flextronics Electronics Technology (Suzhou) Co. Ltd.	Wang Renhua, Jabil Circuit (Shanghai) Ltd.	Gao Yunhang, ZTE Corporation
Yuan Zhang, Huawei Technologies Co., Ltd.		Tang Xuemei, ZTE Corporation

**Members of J-STD-001 Task Group – India (5-22AIN)**

Jithashree Nayakarahalli, Centum  
Electronics Limited

Nagaraja Upadhy, Centum Rakon  
India Pvt. Ltd.

Rentachintala Sudhakar, Electronics  
Test & Development Center

Appanallur Saravanan, Indian  
Institute of Science

Panchapakesan Kannan, Indsoltech  
Tirumalai Phanishayee, IPC

Technology Consulting Pvt Ltd

T. Nanjundaswamy, IPC Technology  
Consulting Pvt Ltd

Chandrashekaraiah Nagaraj, IPC  
Technology Consulting Pvt Ltd

Dilip Rane, IPC Technology  
Consulting Pvt Ltd

Sasikala Jabili, IPC Technology  
Consulting Pvt Ltd

B. J. Srinivas, Kreative Technologies

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## Table of Contents

<b>1 GENERAL</b> .....	1	<b>3 MATERIALS, COMPONENTS AND EQUIPMENT REQUIREMENTS</b> .....	7
1.1 Scope .....	1	3.1 Materials .....	7
1.2 Purpose .....	1	3.2 Solder .....	7
1.3 Classification .....	1	3.2.1 Solder – Lead Free .....	7
1.4 Measurement Units and Applications .....	1	3.2.2 Solder Purity Maintenance .....	7
1.4.1 Verification of Dimensions .....	1	3.3 Flux .....	8
1.5 Definition of Requirements .....	2	3.3.1 Flux Application .....	8
1.5.1 Hardware Defects and Process Indicators .....	2	3.4 Solder Paste .....	8
1.5.2 Material and Process Nonconformance .....	2	3.5 Solder Preforms .....	8
1.6 General Requirements .....	3	3.6 Adhesives .....	8
1.7 Order of Precedence .....	3	3.7 Chemical Strippers .....	8
1.7.1 Conflict .....	3	3.8 Components .....	9
1.7.2 Clause References .....	3	3.8.1 Component and Seal Damage .....	9
1.7.3 Appendices .....	3	3.8.2 Coating Processes .....	9
1.8 Terms and Definitions .....	3	3.9 Soldering Tools and Equipment .....	9
1.8.1 Disposition .....	3	<b>4 GENERAL SOLDERING AND ASSEMBLY REQUIREMENTS</b> .....	9
1.8.2 Electrical Clearance .....	3	4.1 Electrostatic Discharge (ESD) .....	9
1.8.3 FOD (Foreign Object Debris) .....	3	4.2 Facilities .....	9
1.8.4 High Voltage .....	4	4.2.1 Environmental Controls .....	9
1.8.5 Manufacturer (Assembler) .....	4	4.2.2 Temperature and Humidity .....	9
1.8.6 Objective Evidence .....	4	4.2.3 Lighting .....	10
1.8.7 Process Control .....	4	4.2.4 Field Assembly Operations .....	10
1.8.8 Proficiency .....	4	4.3 Solderability .....	10
1.8.9 Solder Destination Side .....	4	4.4 Solderability Maintenance .....	10
1.8.10 Solder Source Side .....	4	4.5 Removal of Component Surface Finishes .....	10
1.8.11 Supplier .....	4	4.5.1 Gold Removal .....	10
1.8.12 User .....	4	4.5.2 Other Metallic Surface Finishes Removal .....	10
1.8.13 Wire Overwrap .....	4	4.6 Thermal Protection .....	10
1.8.14 Wire Overlap .....	4	4.7 Rework of Nonsolderable Parts .....	11
1.9 Requirements Flowchart .....	4	4.8 Preprocessing Cleanliness Requirements .....	11
1.10 Personnel Proficiency .....	5	4.9 General Part Mounting Requirements .....	11
1.11 Acceptance Requirements .....	5	4.9.1 General Requirements .....	11
1.12 General Assembly Requirements .....	5	4.9.2 Lead Deformation Limits .....	11
1.13 Miscellaneous Requirements .....	5	4.10 Hole Obstruction .....	11
1.13.1 Health and Safety .....	5	4.11 Metal-Cased Component Isolation .....	11
1.13.2 Procedures for Specialized Technologies .....	5	4.12 Adhesive Coverage Limits .....	11
<b>2 APPLICABLE DOCUMENTS</b> .....	6	4.13 Mounting of Parts on Parts (Stacking of Components) .....	11
2.1 EIA .....	6	4.14 Connectors and Contact Areas .....	11
2.2 IPC .....	6	4.15 Handling of Parts .....	11
2.3 Joint Industry Standards .....	7		
2.4 ASTM .....	7		
2.5 Electrostatic Discharge Association .....	7		

4.15.1	Preheating .....	11	5.6.3	Wire Staking .....	21
4.15.2	Controlled Cooling .....	12	5.6.4	Land .....	22
4.15.3	Drying/Degassing .....	12	5.6.5	Supported Holes .....	22
4.15.4	Holding Devices and Materials .....	12	5.6.6	SMT .....	22
4.16	Machine (Nonreflow) Soldering .....	12	<b>6</b>	<b>THROUGH-HOLE MOUNTING AND TERMINATIONS</b> .....	<b>23</b>
4.16.1	Machine Controls .....	12	6.1	Through-Hole Terminations – General .....	23
4.16.2	Solder Bath .....	12	6.1.1	Lead Forming .....	24
4.17	Reflow Soldering .....	12	6.1.2	Termination Requirements .....	24
4.17.1	Intrusive Soldering (Paste-in-Hole) .....	12	6.1.3	Lead Trimming .....	25
4.18	Solder Connection .....	12	6.1.4	Interfacial Connections .....	25
4.18.1	Exposed Surfaces .....	13	6.1.5	Coating Meniscus In Solder .....	25
4.18.2	Solder Connection Anomalies .....	13	6.2	Supported Holes .....	26
4.18.3	Partially Visible or Hidden Solder Connections .....	13	6.2.1	Solder Application .....	26
4.19	Heat Shrinkable Soldering Devices .....	14	6.2.2	Through-Hole Component Lead Soldering .....	26
<b>5</b>	<b>WIRES AND TERMINAL CONNECTIONS</b> .....	<b>14</b>	6.3	Unsupported Holes .....	26
5.1	Wire and Cable Preparation .....	14	6.3.1	Lead Termination Requirements for Unsupported Holes .....	26
5.1.1	Insulation Damage .....	14	<b>7</b>	<b>SURFACE MOUNTING OF COMPONENTS</b> .....	<b>27</b>
5.1.2	Strand Damage .....	14	7.1	Surface Mount Device Lead .....	27
5.1.3	Tinning of Stranded Wire .....	14	7.1.1	Plastic Components .....	27
5.2	Solder Terminals .....	15	7.1.2	Forming .....	27
5.3	Bifurcated, Turret and Slotted Terminal Installation .....	15	7.1.3	Unintentional Bending .....	28
5.3.1	Shank Damage .....	15	7.1.4	Flat Pack Parallelism .....	28
5.3.2	Flange Damage .....	15	7.1.5	Surface Mount Device Lead Bends .....	28
5.3.3	Flared Flange Angles .....	15	7.1.6	Flattened Leads .....	28
5.3.4	Terminal Mounting – Mechanical .....	15	7.1.7	Parts Not Configured for Surface Mounting .....	28
5.3.5	Terminal Mounting – Electrical .....	15	7.2	Leaded Component Body Clearance .....	28
5.3.6	Terminal Mounting – Soldering .....	15	7.2.1	Axial-Leaded Components .....	28
5.4	Mounting to Terminals .....	16	7.3	Parts Configured for Butt/I Lead Mounting .....	28
5.4.1	General Requirements .....	16	7.4	Hold Down of Surface Mount Leads/Components .....	28
5.4.2	Turret and Straight Pin Terminals .....	18	7.5	Soldering Requirements .....	28
5.4.3	Bifurcated Terminals .....	18	7.5.1	Misaligned Components .....	29
5.4.4	Slotted Terminals .....	19	7.5.2	Unspecified and Special Requirements .....	29
5.4.5	Hook Terminals .....	20	7.5.3	Bottom Only Chip Component Terminations .....	30
5.4.6	Pierced or Perforated Terminals .....	20	7.5.4	Rectangular or Square End Chip Components – 1, 3 or 5 Side Termination .....	31
5.4.7	Cup and Hollow Cylindrical Terminals – Placement .....	21	7.5.5	Cylindrical End Cap Terminations .....	32
5.5	Soldering to Terminals .....	21	7.5.6	Castellated Terminations .....	33
5.5.1	Bifurcated Terminals .....	21	7.5.7	Flat Gull Wing Leads .....	34
5.5.2	Slotted Terminal .....	21	7.5.8	Round or Flattened (Coined) Gull Wing Leads .....	35
5.5.3	Cup and Hollow Cylindrical Terminals – Soldering .....	21	7.5.9	J-Lead Terminations .....	36
5.6	Jumper Wires .....	21			
5.6.1	Insulation .....	21			
5.6.2	Wire Routing .....	21			

7.5.10	Butt/I Terminations .....	37	10.2	Conformal Coating – Masking .....	51
7.5.11	Flat Lug Leads .....	39	10.3	Conformal Coating – Application .....	51
7.5.12	Tall Profile Components Having Bottom Only Terminations .....	40	10.3.1	Conformal Coating on Components .....	51
7.5.13	Inward Formed L-Shaped Ribbon Leads .....	40	10.3.2	Thickness .....	52
7.5.14	Surface Mount Area Array Packages .....	42	10.3.3	Uniformity .....	52
7.5.15	Bottom Termination Components (BTC) .....	44	10.3.4	Transparency .....	52
7.5.16	Components with Bottom Thermal Plane Terminations (D-Pak) .....	45	10.3.5	Bubbles and Voids .....	52
7.5.17	Flattened Post Connections .....	46	10.3.6	Delamination .....	52
7.5.18	P-Style Terminations .....	47	10.3.7	Foreign Objects Debris .....	52
7.6	Specialized SMT Terminations .....	47	10.3.8	Other Visual Conditions .....	52
<b>8</b>	<b>CLEANING PROCESS REQUIREMENTS</b> .....	48	10.3.9	Inspection .....	52
8.1	Cleanliness Exemptions .....	48	10.3.10	Rework or Touchup of Conformal Coating .....	53
8.2	Ultrasonic Cleaning .....	48	10.4	Encapsulation .....	53
8.3	Post-Solder Cleanliness .....	48	10.4.1	Application .....	53
8.3.1	Foreign Object Debris (FOD) .....	48	10.4.2	Performance Requirements .....	53
8.3.2	Flux Residues and Other Ionic or Organic Contaminants .....	48	10.4.3	Rework of Encapsulant Material .....	53
8.3.3	Post-Soldering Cleanliness Designator .....	48	10.4.4	Encapsulant Inspection .....	53
8.3.4	Cleaning Option .....	48	10.5	Staking .....	53
8.3.5	Test for Cleanliness .....	48	10.5.1	Staking – Application .....	53
8.3.6	Testing .....	49	10.5.2	Staking – Adhesive .....	54
<b>9</b>	<b>PCB REQUIREMENTS</b> .....	50	10.5.3	Staking – Inspection .....	54
9.1	Printed Circuit Board Damage .....	50	<b>11</b>	<b>WITNESS (TORQUE/ANTI-TAMPERING) STRIPE</b> .....	54
9.1.1	Blistering/Delamination .....	50	<b>12</b>	<b>PRODUCT ASSURANCE</b> .....	54
9.1.2	Weave Exposure/Cut Fibers .....	50	12.1	Hardware Defects Requiring Disposition .....	54
9.1.3	Haloing .....	50	12.2	Inspection Methodology .....	54
9.1.4	Edge Delamination .....	50	12.2.1	Process Verification Inspection .....	54
9.1.5	Land/Conductor Separation .....	50	12.2.2	Visual Inspection .....	54
9.1.6	Land/Conductor Reduction in Size .....	50	12.2.3	Sampling Inspection .....	55
9.1.7	Flexible Circuitry Delamination .....	50	12.3	Process Control Requirements .....	55
9.1.8	Flexible Circuitry Damage .....	50	12.3.1	Opportunities Determination .....	55
9.1.9	Burns .....	50	12.4	Statistical Process Control .....	55
9.1.10	Non-Soldered Edge Contacts .....	50	<b>13</b>	<b>REWORK AND REPAIR</b> .....	56
9.1.11	Measles .....	50	13.1	Rework .....	56
9.1.12	Crazing .....	51	13.2	Repair .....	56
9.2	Marking .....	51	13.3	Post Rework/Repair Cleaning .....	56
9.3	Bow and Twist (Warpage) .....	51	<b>APPENDIX A</b>	<b>Guidelines for Soldering Tools and Equipment</b> .....	57
9.4	Depanelization .....	51	<b>APPENDIX B</b>	<b>Minimum Electrical Clearance – Electrical Conductor Spacing</b> .....	59
<b>10</b>	<b>COATING, ENCAPSULATION AND STAKING (ADHESIVE)</b> .....	51	<b>APPENDIX C</b>	<b>J-STD-001 Guidance on Objective Evidence of Material Compatibility</b> .....	61
10.1	Conformal Coating – Materials .....	51			

**Figures**

Figure 1-1	Overwrap .....	4
Figure 1-2	Overlap .....	4
Figure 4-1	Hole Obstruction .....	11
Figure 4-2	Acceptable Wetting Angles .....	13
Figure 5-1	Flange Damage .....	15
Figure 5-2	Flare Angles .....	15
Figure 5-3	Terminal Mounting – Mechanical .....	16
Figure 5-4	Terminal Mounting .....	16
Figure 5-5	Insulation Clearance Measurement .....	16
Figure 5-6	Service Loop for Lead Wiring .....	17
Figure 5-7	Stress Relief Examples .....	17
Figure 5-8	Wire and Lead Wrap Around .....	18
Figure 5-9	Bifurcated Terminal Side Route Placement with Wrap .....	18
Figure 5-10	Bifurcated Terminal Side Route Placement – Straight Though and Staked .....	19
Figure 5-11	Bifurcated Terminal Top and Bottom Route Connection .....	19
Figure 5-12	Slotted Terminal .....	19
Figure 5-13	Hook Terminal Connections .....	20
Figure 5-14	Pierced or Perforated Terminal Wire Placement .....	20
Figure 5-15	Solder Height .....	21
Figure 6-1	Component Lead Stress Relief Examples ....	23
Figure 6-2	Lead Bends .....	24
Figure 6-3	Lead Trimming .....	25
Figure 6-4	Vertical Fill Example .....	25
Figure 7-1	Surface Mount Device Lead Forming .....	27
Figure 7-2	Surface Mount Device Lead Forming .....	27
Figure 7-3	Bottom Only Terminations .....	30
Figure 7-4	Rectangular or Square End Chip Components .....	31
Figure 7-5	Cylindrical End Cap Terminations .....	32
Figure 7-6	Castellated Terminations .....	33
Figure 7-7	Flat Gull Wing Leads .....	34
Figure 7-8	Round or Flattened (Coined) Gull Wing Leads .....	35
Figure 7-9	J Leads .....	36
Figure 7-10	Butt/I Connection for Modified Through-Hole Leads .....	37
Figure 7-11	Butt/I Connection for Solder Charged Leads .....	38
Figure 7-12	Flat Lug Leads .....	39
Figure 7-13	Tall Profile Components Having Bottom Only Terminations .....	40
Figure 7-14	Inward Formed L-Shaped Ribbon Lead .....	41
Figure 7-15	BGA Solder Ball Clearance .....	43
Figure 7-16	Bottom Termination Component .....	44

Figure 7-17	Bottom Thermal Plane Termination .....	45
Figure 7-18	Flattened Post Termination .....	46
Figure 7-19	P-Style Termination .....	47

**Tables**

Table 1-1	Design, Fabrication and Acceptability .....	3
Table 3-1	Maximum Limits of Solder Bath Contaminant ....	8
Table 4-1	Solder Anomalies .....	13
Table 5-1	Allowable Strand Damage .....	15
Table 5-2	Terminal Mounting Minimum Soldering Requirements .....	16
Table 5-3	Turret and Straight Pin Wire Placement .....	18
Table 5-4	AWG 30 and Smaller Wire Wrap Requirements .....	18
Table 5-5	Bifurcated Terminal Wire Placement – Side Route with Wrap .....	18
Table 5-6	Bifurcated Terminal Side Route Straight-Through Staking Requirements .....	19
Table 5-7	Bifurcated Terminal Wire Placement – Bottom Route .....	19
Table 5-8	Hook Terminal Wire Placement .....	20
Table 5-9	Pierced or Perforated Terminal Wire Placement .....	20
Table 5-10	Solder Requirements Wire to Post .....	21
Table 6-1	Component to Land Clearance .....	23
Table 6-2	Components with Spacers .....	23
Table 6-3	Lead Bend Radius .....	24
Table 6-4	Protrusion of Leads in Supported Holes .....	24
Table 6-5	Protrusion of Leads in Unsupported Holes .....	24
Table 6-6	Supported Holes with Component Leads, Minimum Acceptable Conditions .....	25
Table 6-7	Unsupported Holes with Component Leads, Minimum Acceptable Conditions .....	26
Table 7-1	SMT Lead Forming Minimum Lead Length (L) .....	27
Table 7-2	Surface Mount Components .....	29
Table 7-3	Dimensional Criteria – Bottom Only Chip Component Terminations .....	30
Table 7-4	Dimensional Criteria – Rectangular or Square End Chip Components – 1, 3 or 5 Side Termination .....	31
Table 7-5	Dimensional Criteria – Cylindrical End Cap Terminations .....	32
Table 7-6	Dimensional Criteria – Castellated Terminations .....	33
Table 7-7	Dimensional Criteria – Flat Gull Wing Leads ...	34
Table 7-8	Dimensional Criteria – Round or Flattened (Coined) Gull Wing Leads .....	35
Table 7-9	Dimensional Criteria – J Leads .....	36
Table 7-10	Dimensional Criteria – Butt/I Connections .....	37

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Table 7-11	Dimensional Criteria – Butt/I Terminations – Solder Charged Terminations .....	38
Table 7-12	Dimensional Criteria – Flat Lug Leads .....	39
Table 7-13	Dimensional Criteria – Tall Profile Components Having Bottom Only Terminations .....	40
Table 7-14	Dimensional Criteria – Inward Formed L-Shaped Ribbon Leads .....	41
Table 7-15	Dimensional Criteria – Ball Grid Array Components with Collapsing Balls .....	43
Table 7-16	Ball Grid Array Components with Noncollapsing Balls .....	43
Table 7-17	Column Grid Array .....	43
Table 7-18	Dimensional Criteria – BTC .....	44
Table 7-19	Dimensional Criteria – Bottom Thermal Plane Terminations .....	45
Table 7-20	Dimensional Criteria Flattened Post Connections .....	46
Table 7-21	Dimensional Criteria – P-Style Terminations ....	47
Table 8-1	Designation of Surfaces to be Cleaned .....	48
Table 8-2	Cleanliness Testing Designators .....	48
Table 10-1	Coating Thickness .....	52
Table 12-1	Magnification Aid Applications for Solder Connections .....	55
Table 12-2	Magnification Aid Applications – Other .....	55